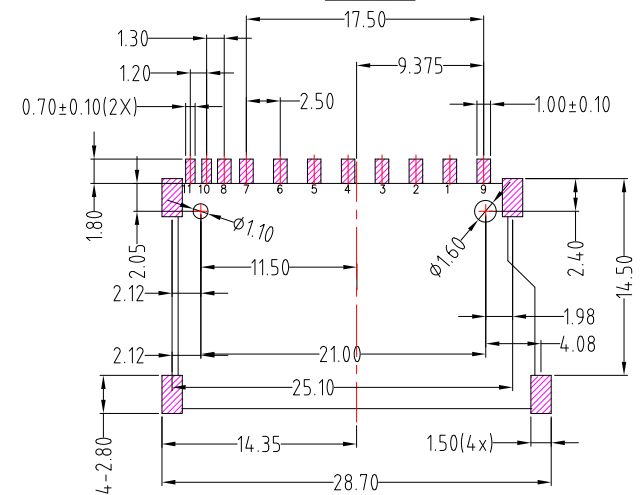
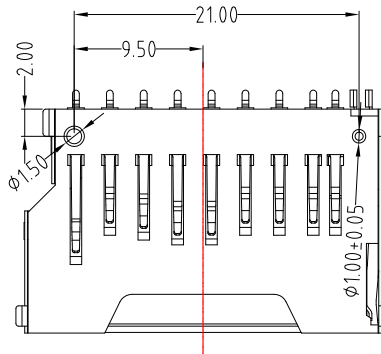
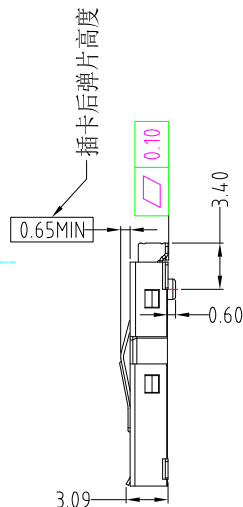
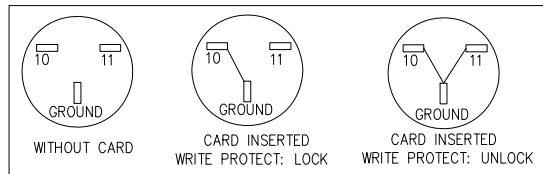
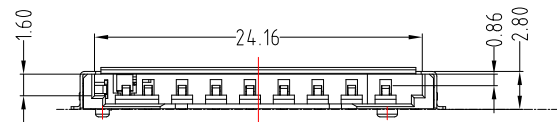
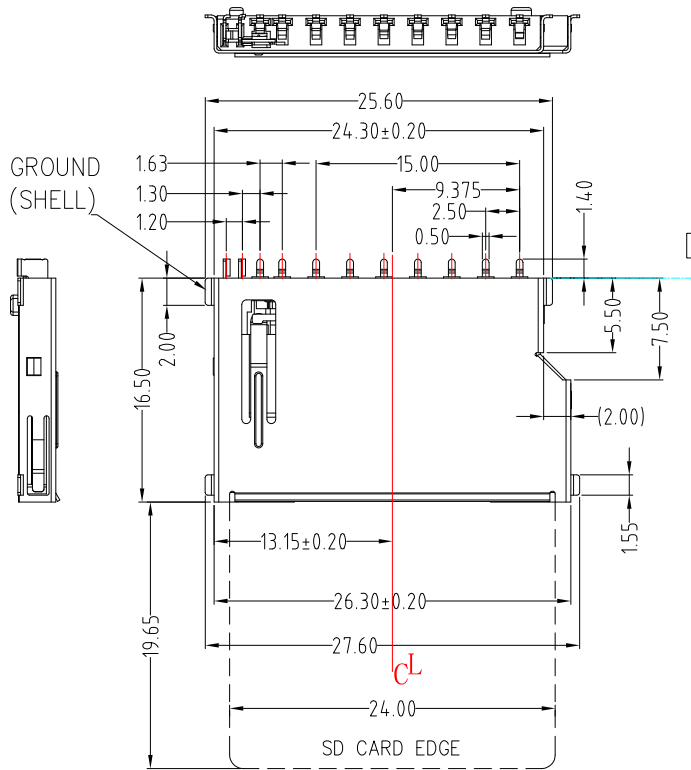




PAD AREA
KEEP OUT AREA

RECOMMENDED P.C.B LAYOUT

SD CARD PIN DESIGN

PIN NO.	NAME	DESCRIPTION
1#	CD/DAT3	CARD DETECT/DATA I/O
2#	CMD	COMMAND
3#	VSS1	GROUND
4#	VDD	POWER
5#	CLK	CLOCK
6#	VSS2	GROUND
7#	DAT0	DATA I/O
8#	DAT1	DATA I/O
9#	DAT2	DATA I/O
10#	CD	Card Detect pin
11#	WP	Write Protect pin

1.MATERIAL:

- 1.1 HOUSING: LCP
- 1.2 CONTACT: PHOSPHOR BRONZE
- 1.3 COVER: BRASS

2.PLATING:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.ELECTRICAL & MECHANICAL PARAMETER

- 3.1 RATING: 250V , 0.5A
- 3.2 CONTACT RESISTANCE: 100mΩ MAX
- 3.3 INSULATION RESISTANCE: 1000MΩ MIN
- 3.4 WITHSTANDING STRENGTH: 500V AC
- 3.5 INSERTION FORCE: 10N MAX
- 3.6 SEPARATION FORCE: 2N MIN
- 3.7 OPERATING TEMPERATURE: -25°C ~ 90°C

 东莞市高迪电子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS
OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 06/09/23
DATE: 06/09/23
DATE: 06/09/23

MAT'L
FINISH
SCALE: 1 : 1
SHEET NO. 1 of 3

TITLE: CONNECTOR
MODLE: SD 短體卡座 H3.09mm
DWG NO. SD-TF125001-HF-S267
PART NO. SD-TF125001-HF-S267

SIZE: A4
VER: R1